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Example:GooLED-SEO-4868-B-1,2 Example:GooLED-SEO-48 1 - 2 Height (mm) Anodising Color B-Black

C-Clear

Z-Custom

Ex.order code - 12

Notes:

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- Mentioned models are an extraction of full product range.

- For specific mechanical adaptations please contact MingfaTech.

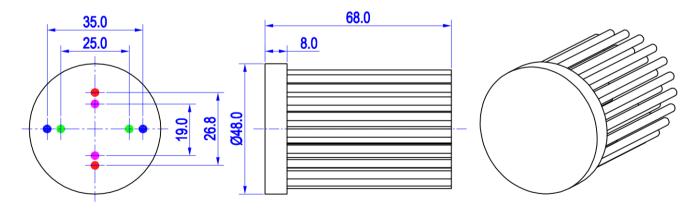
- MingfaTech reserves the right to change products or specifications without prior notice.

means option 1 and 2 combined

details Combinations available

Mounting Options - see graphics for

MOUNTING OPTION	Module type	Holder NO.	LEDiL products		THREAD	THREAD	THREAD HOLE
			Olivia series	Ronda series	INKEAD	DEPTH	DISTANCE
1	COB Size 13.5×13.5mm	/	FN14637-S;	FN15972-xxx; FN15971-xxx; FN15969-xxx;	M3	6.5mm	19.0mm/ 2-@180°
2		BJB Holder 47.319.2021.50			M3	6.5mm	25.0mm/ 2-@180° (Zhaga book 11)
		AAG.STUCCHI 8101-G2					
3		/	FN14637-S; FN14828-M;	FN15xxx-xx;	М3	6.5mm	26.8mm/ 2-@180°
4	COB Size 19×19mm	BJB Holder 47.319.2021.50			М3	6.5mm	35.0mm/ 2-@180° (Zhaga book 3)
4		AAG.STUCCHI 8101-G2					



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GooLED-SEO-4868 Pin Fin Heat Sink Φ48mm for Seoul

The product deta table

GooLED	Model No.	GooLED-SEO-4868		
GOOLED	Heatsink Size	Φ48xH68mm		
	Heatsink Material	AL1070		
	Finish	Black Anodized		
	Weight (g)	93.0		
	Dissipated power (Ths-amb,50°C)	11.5 (W)		
	Cooling surface area (mm²)	31383		
	Thermal Resistance (Rhs-amb)	4.35 (°C/W)		

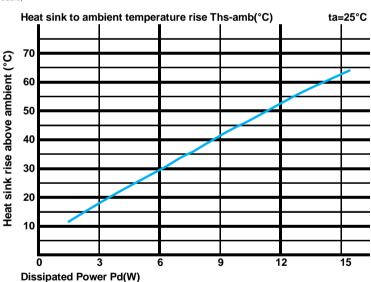
The thermal data table

* Please be aware the dissipated power Pd is not the same as the electrical power Pe of a LED module.

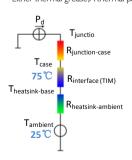
*To calculate the dissipated power please use the following formula: $Pd = Pe \times (1 - \eta L)$.

Pd - Dissipated power ; Pe - Electrical power ; ηL = Light effciency of the LED module;

Pd = Pe x (1-ηL)		Heat sink to ambient thermal resistance Rhs-amb (°C/W)	Heat sink to ambient temperature rise Ths-amb (°C)	
		GooLED-SEO-4868		
Dissipated Power Pd(W)	3.0	6.00	18.0	
	6.0	4.83	29.0	
	9.0	4.56	41.0	
	12.0	4.33	52.0	
	15.0	4.13	62.0	



*The aluminum substrate side of the package outer shell is thermally connected to the heat sink via TIM (Thermal interface material). MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler. Either thermal grease, A thermal pad or a phase change thermal pad thickness 0.1-0.15mm is recommended.



*Thermal resistance is a heat property and a measurement of a temperature difference by which an object or material resists a heat flow. Geometric shapes are different, the thermal resistance is different. Formula: $\theta = (Ths - Ta)/Pd$

 θ - Thermal Resistance [°C/W]; Ths - Heatsink temperature; Ta - Ambient temperature;

*The thermal resistance between the junction section of the light-emitting diode and the aluminum substrate side of the package outer shell is R_{junction-case}, the thermal resistance of the TIM outside the package is R_{interface (TIM)} [°C/W], the thermal resistance with the heat sink is $R_{heatsink-ambient}$ [°C/W], and the ambient temperature is $T_{ambient}$ [°C].

*Thermal resistances outside the package $R_{interface \, (TIM)}$ and $R_{heatsink-ambient}$ can be integrated into the thermal resistance $\mathsf{R}_{case-ambient}$ at this point. Thus, the following formula is also used: $T_{junction} = (R_{junction-case} + R_{case-ambient}) \cdot Pd + T_{ambient}$

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